

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN-COL 3mm X 2mm Exp. Pad

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**TOTAL MASS (g) : 0.013947**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000901	1000000	64603.53125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.005090	975000	364963.3125		
		Iron (Fe)	7439-89-6	0.000125	24000	8962.75390625		
		Phosphorus (P)	7723-14-0	0.000002	300	143.404067993		
		Zinc (Zn)	7440-66-6	0.000004	700	286.808135986		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.005221</b>	<b>1000000</b>	<b>374356.3125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000185	1000000	13236.6601562		
		<b>External Plating Total:</b>				<b>0.000185</b>	<b>1000000</b>	<b>13236.6601562</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000103	1000000	7385.30908203		
		<b>Internal Plating Total:</b>				<b>0.000103</b>	<b>1000000</b>	<b>7385.30908203</b>
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000006	50000	430.212188721		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000036	300000	2581.27319336		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000078	650000	5592.7578125		
<b>Die Attach Total:</b>				<b>0.000120</b>	<b>1000000</b>	<b>8604.24316406</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000958	130000	68690.546875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.006338	860000	454447.4375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000074	10000	5305.95068359		
		<b>Encapsulation Total:</b>				<b>0.007370</b>	<b>1000000</b>	<b>528443.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000047	1000000	3369.99536133		
					<b>TOTAL MASS (g) :</b>	<b>0.013947</b>		